BQCSC-XXXMX-XXXXT - 5.0x3.2 Crystals

dille

technologies



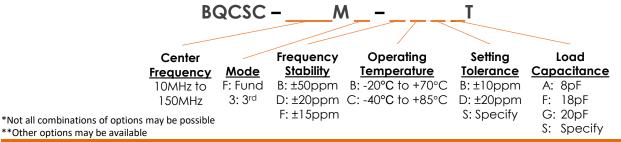
SMD Construction Standard 5.0x3.2mm Package Size

High Stability Over Temp

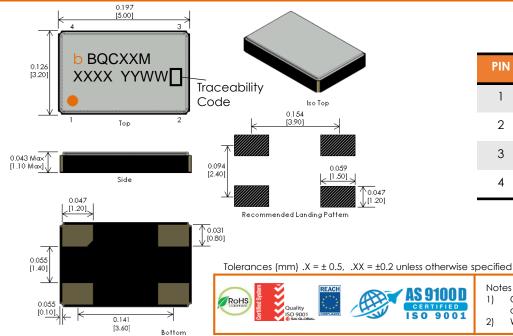
Crystals

#blileytakesyoufurther

Part Number Configuration



Physical Specifications



PIN	FUNCTION			
1	Crystal			
2	Ground			
3	Crystal			
4	Ground			



- Connection Pads: Gold(10-40 µ in.) 1) over Nickel (100-250 µ in.)
 - 2) Weight = 1.5gms typical

DISCLAIMER: Billey Technologies, Inc. reserves the right to make changes to the product(s) and or information contained herein without notice. No liability is assumed as a result of their use or application. No intellectual property rights accompany the sale or delivery of any such product(s) or information.



Performance Specifications

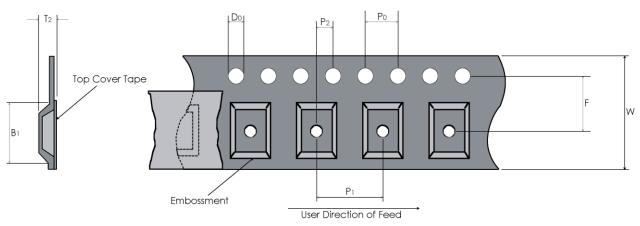
Parameter	Conditions	Fundamental	3 rd overtone	Unit
Frequency Range		10.0 – 60.0	40.0 –150.0	MHz
Frequency Tolerance	@ + 25°C	±50 Max (s	ee options)	ppm
Frequency Stability		±100 Max (s	see options)	ppm
Aging	Max 1 st Year	±	3.0	ppm
	8.0 – 12.0 MHz	100		Ω
	13.0 – 20.0 MHz	80		Ω
Equivalent Series Resistance (max)	20.0 – 29.0 MHz	50		Ω
(many	30.0 – 60.0 MHz	40		Ω
	40.0 – 150.0 MHz		80	Ω
Insulative Resistance	Min @ 100Vdc ±15Vdc	5	00	ΜΩ
Drive Level		10 Тур,	200 Max	μW
C0 (Shunt Capacitance)	Max	5	5.0	рF
CL (Load Capacitance)	Per Option (typical)	6-20 (see options)		рF
DLD	50nW to 100µW	±10	Max	ppm
RLD	50nW to 100µW	20%	Max	Ω
Operating Temp Range		-20 to +70	/ -40 to +85	°C
Storage Temp Range		-55 to	o +125	°C
Sealing Method		Seam	n Weld	
Moisture Sensitivity Level	1			

DISCLAIMER: Billey Technologies, Inc. reserves the right to make changes to the product(s) and or information contained herein without notice. No liability is assumed as a result of their use or application. No intellectual property rights accompany the sale or delivery of any such product(s) or information.



Tape and Reel

Embosed Carrier Dimensions (8mm, 12mm, 16mm, 24mm Tape Only)



Tape Dimensions (mm) Reel Dimensions (mm)									
W	F	Do	Ро	Р1	P2	В1	T2	Outside Dia.	Parts / Reel
12	5.5	1.5	4.0	8	2.0	5.5	1.7	180	1,000

Recommended Reflow Profile

Reflow Profile: in accordance to IPC/JEDEC J-STD-020 (Latest Revision)

Additional Notes:

- This part has been designed for pick and place reflow soldering
- This part may be reflowed once
- This part should not be reflowed in the inverted position

Packaging

Packaging: All packaging must conform to ESD Controls detailed in ANSI/ESD S20.20 (Latest Revision)

DISCLAIMER: Billey Technologies, Inc. reserves the right to make changes to the product(s) and or information contained herein without notice. No liability is assumed as a result of their use or application. No intellectual property rights accompany the sale or delivery of any such product(s) or information.